



## Device Material Content

5555 NE Moore Ct.  
Hillsboro OR 97124  
(503) 268-8000

**Package: 16 SOIC with SnPb Plating**  
**Total Device Weight 0.42 Grams**

June, 2004	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
<b>Die</b>	4.82%	0.020			Silicon	7440-21-3	Die size: 3.96 x 6.10 mm
<b>Mold</b>	70.25%	0.295	55.63%	0.234	Silica Fused	60676-86-0	Mold Compound Density between 1.7 and 1.9 grams/cc 60 to 90% Silica Fused (LSC uses 67.20% in our calculation) 10 to 30% Epoxy Resin (LSC uses 20.0% in our calculation). 5 to 10% Phenol Resin (LSC uses 7.5% in our calculation). 1 to 3% Brominated Epoxy Resin (LSC uses 2.0% in our calculation). 1 to 5% Antimony Trioxide (LSC uses 3.0% in our calculation) 0.1 to 0.5% Carbon black (LSC uses 0.3% in our calculation)
			7.02%	0.030	Epoxy Resin	129915-35-1	
			4.57%	0.019	Phenol Resin	26834-02-6	
			1.40%	0.006	Brominated Epoxy Resin	68928-70-1	
			1.40%	0.006	Antimony Trioxide	1309-64-4	
			0.21%	0.001	Carbon black	1333-86-4	
<b>D/A Epoxy</b>	0.41%	0.001	0.47%	0.002	Silver (Ag)	7440-22-4	Die attach epoxy Density: 4 grams/cc (silver content: 60-100%;LSC uses 80% in our calculation).
			0.12%	0.0005	other	-	
<b>Wire</b>	0.11%	0.0005			Gold (Au)	7440-57-5	1.0 mil wire diameter; 1 wire for each package lead; wire length 3 mm
<b>Lead Plating</b>	1.27%	0.005	1.08%	0.005	Tin (Sn)	7440-31-5	Nominal: 85% Sn, 15% Pb Thickness is 0.015mm
			0.19%	0.0010	Lead (Pb)	7439-92-1	
<b>Leadframe</b>	22.97%	0.096	22.39%	0.094	Copper (Cu)	7440-50-8	Nominal Leadframe composition: Cu: 97.46% Zn: 0.12% Fe: 2.35% P: 0.07% Leadframe thickness is nominal (per Case Outline).
			0.03%	0.0001	Zinc (Zn)	7440-66-6	
			0.54%	0.0023	Iron (Fe)	7439-89-6	
			0.02%	0.0001	Phosphorus (P)	7723-14-0	

**Notes:**

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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